



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} (@ T _J Max) (Note 7) | R _{DS(ON)} | I _D T _C = +25°C |
|--|----------------------------|--|
| 1000V | 2.2Ω@V _{GS} = 10V | 6A |

Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

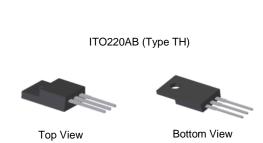
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

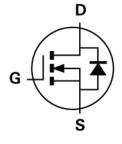
Features

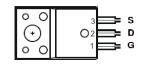
- Low Input Capacitance
- High BV_{DSS} Rating for Power Application
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: ITO220AB (Type TH)
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)







Equivalent Circuit

Top View Pin Out Configuration

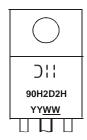
Ordering Information (Note 4)

| - 7 | | | | | |
|-----|---------------|--------------------|----------------|--|--|
| | Part Number | Case | Packaging | | |
| | DMN90H2D2HCTI | ITO220AB (Type TH) | 50 Pieces/Tube | | |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



☐ Hamaufacturer's Marking

90H2D2H = Product Type Marking Code

YYWW = Date Code Marking

YY or YY = Last Two Digits of Year (ex: 16 = 2016)

WW or WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--------------------------------------|-------------------------|-----------------|-------|------|
| Drain-Source Voltage | | V_{DSS} | 900 | V |
| Gate-Source Voltage | | V_{GSS} | ±30 | V |
| Continuous Drain Current (Notes 5) | T _C = +25°C | - | 6 | Δ |
| V _{GS} = 10V (Note 6) | $T_{C} = +100^{\circ}C$ | ID | 4 | ^ |
| Pulsed Drain Current | | I _{DM} | 24 | Α |
| Avalanche Current, L = 60mH (Note 7) | | I _{AS} | 3.5 | Α |
| Avalanche Energy, L = 60mH (Note 7) | | E _{AS} | 360 | mJ |

Thermal Characteristics

| Characteristic | | Symbol | Max | Unit |
|---|---|-----------------|-------------|------|
| Power Dissipation (Note 5) | $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$ | P_{D} | 40 14 | W |
| Thermal Resistance, Junction to Case (Note 5) | $T_C = +25$ °C | $R_{\theta JC}$ | 3.6 | °C/W |
| Operating and Storage Temperature Range | | T_J, T_{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

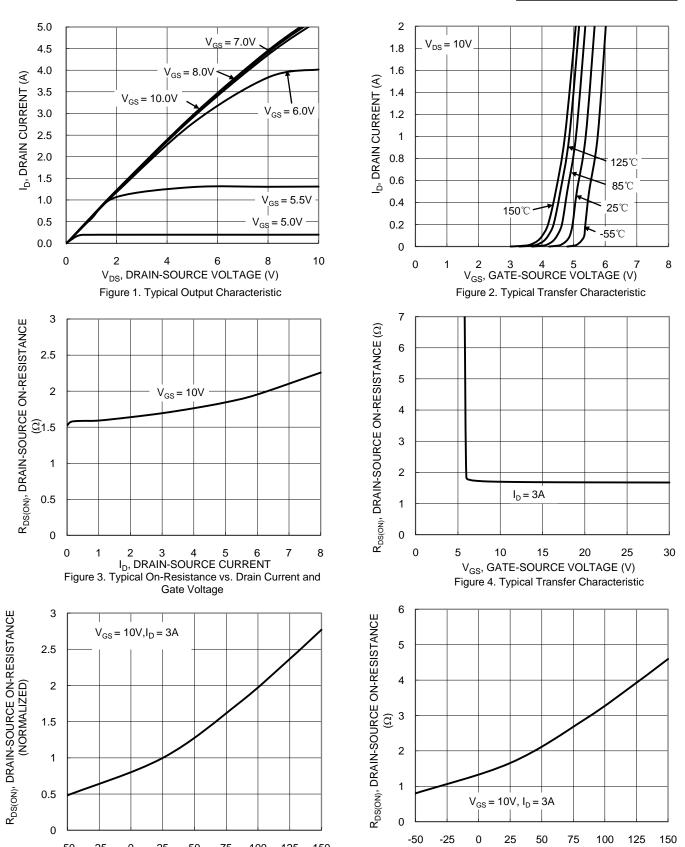
| | | | _ | | | | |
|------------------------------------|---------------------|-----|------|-----|------|---|--|
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 900 | | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μA | $V_{DS} = 900V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | 100 | nA | $V_{GS} = \pm 30V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 3 | 4 | 5 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 1.7 | 2.2 | Ω | $V_{GS} = 10V, I_D = 3A$ | |
| Diode Forward Voltage | V _{SD} | _ | 0.85 | 1.2 | V | $V_{GS} = 0V$, $I_S = 6A$ | |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | | |
| Input Capacitance | C _{iss} | _ | 1487 | _ | | \\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | |
| Output Capacitance | Coss | _ | 113 | _ | pF | $V_{DS} = 25V$, $f = 1MHz$, $V_{GS} = 0V$ | |
| Reverse Transfer Capacitance | C _{rss} | _ | 1 | _ | | | |
| Gate Resistance | Rg | _ | 4.7 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge | Q_g | _ | 20.3 | _ | | V _{DD} = 720V, I _D = 6A, V _{GS} = 10V | |
| Gate-Source Charge | Q _{gs} | _ | 6.4 | _ | nC | | |
| Gate-Drain Charge | Q_{gd} | _ | 6.1 | _ | | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 39 | _ | - ns | $V_{DD} = 450V, V_{GS} = 10V,$ $R_g = 25\Omega, I_D = 6A$ | |
| Turn-On Rise Time | t _R | _ | 49 | _ | | | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 51 | _ | | | |
| Turn-Off Fall Time | t _F | _ | 31 | _ | | | |
| Body Diode Reverse Recovery Time | t _{RR} | _ | 607 | _ | ns | I _F = 6A, dl/dt = 100A/μs | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 8.1 | _ | μC | 71F = 0A, αί/αι = 100A/μ5 | |

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Drain current limited by maximum junction temperature.
- 7. Guaranteed by design. Not subject to production testing. 8. Short duration pulse test used to minimize self-heating effect.







0

25

50

T_J, JUNCTION TEMPERATURE (°C)
Figure 5. On-Resistance Variation with Junction

Temperature

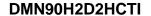
75

100

150

 T_J , JUNCTION TEMPERATURE ($^{\circ}$)

Figure 6. On-Resistance Variation with Junction Temperature





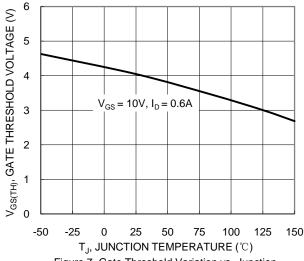
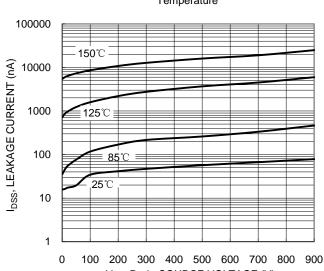
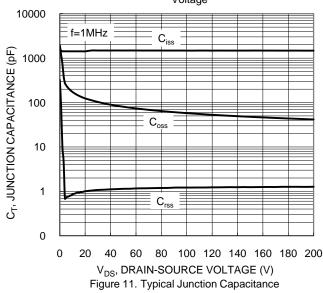


Figure 7. Gate Threshold Variation vs. Junction Temperature



V_{DS}, Drain-SOURCE VOLTAGE (V) Figure 9. Typical Drain-Source Leakage Current vs. Voltage



5 4.5 $V_{GS} = 0V$ 4 IS, SOURCE CURRENT (A) 3.5 3 2.5 2 $T_J = 85^{\circ}C$ 1.5 $T_J = 125^{\circ}C$ 1 $\Gamma_{\rm J} = 25^{\circ}\rm C$ $T_{J} = 150^{\circ}C$ 0.5 $T_1 = -55^{\circ}C$ 0 0 0.3 0.6 0.9 1.2 V_{SD}, SOURCE-DRAIN VOLTAGE (V)

Figure 8. Diode Forward Voltage vs. Current

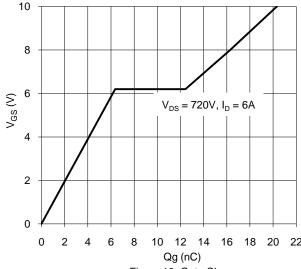


Figure 10. Gate Charge

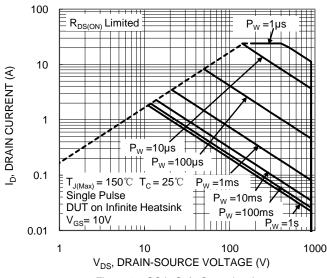
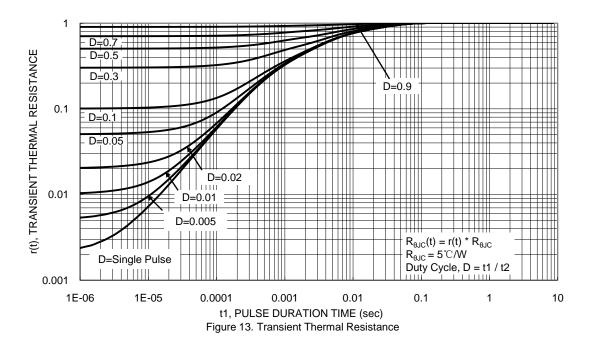


Figure 12. SOA, Safe Operation Area



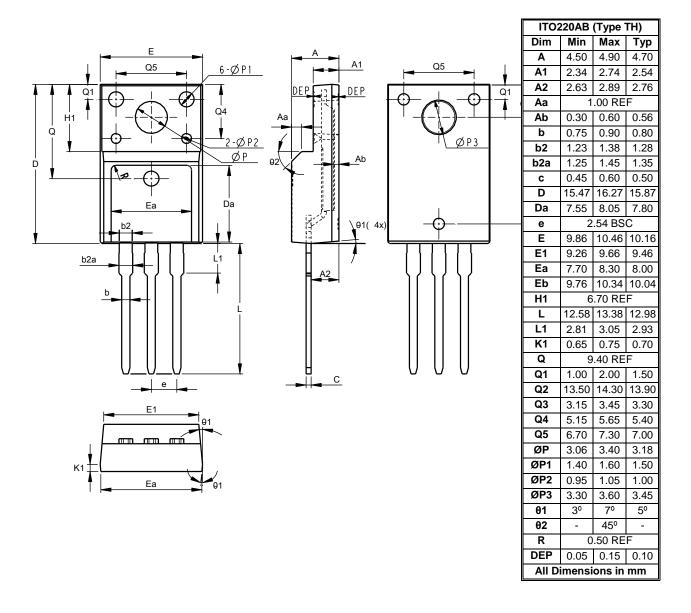




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

ITO220AB (Type TH)





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